

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Yuji Okawa  
Appl. No. : Unknown  
Filed : Herewith  
For : WAFER BACK SURFACE  
TREATING METHOD AND  
DICING SHEET ADHERING  
APPARATUS  
Examiner : Unknown  
Group Art Unit : Unknown

## CERTIFICATE OF MAILING

I hereby certify that this correspondence and all marked attachments are being deposited with the United States Postal Service as express mail No. EV 308023014 in an envelope addressed to: MAIL STOP PATENT APPLICATION, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on

March 25, 2004

(Date)

  
Katsuhiko Arai, Reg. No. 43,315

PRELIMINARY AMENDMENT

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

Prior to examination on the merits, please amend the above-identified application as follows.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks/Arguments** begin on page 5 of this paper.